ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					nterials and	als and Mfg Information				
upplier Inform	ation														
Company name*			Company unique ID			τ	Unique ID Authority					Response Date*			
onsemi											2024-	2024-05-21			
Contact Name		Ti	Title - Contact			1	Phone - Contact*				Emai	Email - Contact*			
Product-Env-Stewa	rds	Pr	Product Enviro Compliance				NA				Prod	Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			1	Phone - Representative*				Emai	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Prod	Product-Env-Stewards@onsemi.com			
Requeste	Requester Item Number Mfr Item		em Number Mfr Item Name				Effective Date	Versi	on	Manufacturing Site		Weight*	UOM	Unit Type	
		NVMFS5C442NWFA T6-D3F 40V NFI FT1G		T		2024-05-21 MY1			100.77	mg	Each				
Ianufacturing l	Proccess Information	1													
Terminal I	Terminal Plating / Grid Array Material Te			erminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Temperature Max Time at Pe		eak Tempe	rature Numl	per of Reflow Cyc	cles			
Matte Tin (Sn) - annealed		CU A	CU Alloy 1				260		С	30	sec	onds 3			
omments															
vel 1 - maximum ti	ime at peak temperature d	luring solder	ring is 10-30	seconds											
or more informatio	on regarding material com	position plea	ase refer to	page 3					· · · · · · · · · · · · · · · · · · ·						

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Isability and the Company's remedies for issues that arise regarding information the Supplier provides in this fo										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	4.8	mg	Supplier	Iron (Fe)	7439-89-6		0.0048	mg
			Supplier	Copper (Cu)	7440-50-8		4.7938	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0014	mg
Die	2.0	mg	Supplier	Silicon (Si)	7440-21-3		2	mg
Die Attach Solder	2.33	mg	Supplier	Silver (Ag)	7440-22-4		0.0582	mg
			A	Lead (Pb)	7439-92-1	7a	2.1553	mg
			Supplier	Tin (Sn)	7440-31-5		0.1165	mg
Lead Frame	47.6	mg	Supplier	Silver (Ag)	7440-22-4		0.0286	mg
			Supplier	Iron (Fe)	7439-89-6		0.0476	mg
			Supplier	Copper (Cu)	7440-50-8		47.5096	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0143	mg
Mold Compound-Black	42.24	mg		Epoxy resin	proprietary data		3.168	mg
			Supplier	Phenolic Resin	Proprietary Data		1.056	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.168	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2112	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		34.6368	mg
Plating	1.7	mg	Supplier	Tin (Sn)	7440-31-5		1.7	mg
Wire Bond - Cu	0.1	mg	Supplier	Copper (Cu)	7440-50-8		0.1	mg